

Quarterly Reliability Monitoring Results

Quarters: Q1/2022 to Q4/2023

Based on structural similarity

Supplier Nexperia B.V. Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test		User Part Number BZX384-C3V3-Q Part Description										
									Nexperia DHAM			
									SMD package			
		Test Conditions	Duration	# Lots	# Quantity	# Rejects						
			TEST									
			Pre- and Post-Stress									
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below						
I		JESD22-A113										
	DC	Bake Tamb = 125 °C	24 hours									
# A1	PC Preconditioning	Soak Tamb = 85 °C, RH = 85% Reflow soldering	168 hours 3 cycles	1514	64430	0						
# AI	Treconditioning	MIL-STD-750-1	3 Cycles	1314	04430	0						
	HTRB	M1038 Method A										
		Tj = Tjmax, VR = 80 % of rated reverse										
# B1	Bias	voltage	1000 hours	250	11400	0						
		MIL-STD-750-1										
		M1038 Method B										
	SSOP	Tj = Tjmax, $Iz = 100%$ of max. datasheet										
# B1b	Steady State Operational	reverse current	1000 hours	44	1920	0						
	TC	JESD22-A104				_						
# A4	Temperature Cycling	-65 °C to Tjmax, not to exceed 150°C	1000 cycles	311	14080	0						
	UHAST	JESD22-A118										
# A3 or	Unbiased HAST	Tamb = 130 °C, RH = 85 %										
" 7(3 C 1	Olibiased Fixes	JESD22-A102	- 96 hours	311	14080	0						
	AC	Tamb = 121 °C, RH = 100 %										
# A3 alt	Autoclave	Pressure = 205 kPa (29.7 psia)										
		, ,										
	H3TRB	JESD22-A101										
	High Humidity High	Tamb = 85 °C, RH = 85%, VR = 80 % of										
# A2 alt	Temperature Reverse Bias	rated reverse voltage ^[1]	1000 hours	311	14080	0						
		MIL-STD-750 Method 1037										
	IOL	ton = toff, devices powered to insure ΔTj =										
# A5	Intermittent Operating Life	100 °C for 15000 cycles	1000 hours	312	14120	0						
		750000 4444										
# 60	RSH Resistance to Solder Heat	JESD22-A111	10 -	260	0070	0						
# C8	Resistance to Solder Heat	260 °C ± 5 °C	10 s	269	8070	0						
# C10	SD Solderability	1-STD-002		10	6660	0						
# C10	Solderability	J-STD-002	445)/	19	6660	0						

^[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia					
DHAM	Zener	11400	0	0,37	2,68E+09

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